Tool ID: 703
Tool Location: 137

Equipment Information Sheet

Hamatech Wafer Processor Develop 1

Manager: Sherri Ellis 607-255-2329
Backup: James Crawford 607-254-5895
Backup: Giovanni Sartorello 607-254-4853

Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

SAFETY

- Stay away from chamber top during process
- Do not reach into chamber top during process
- Strong bases used in process

USAGE RESTRICTIONS
SCHEDULING/SIGN-UP RESTRICTIONS

Minimum Tool Time: 0 minutes

- None

MATERIALS COMPATIBILITY CATEGORY

Tool Category 5: Class A and B Metals and Compounds

Allowed	Not Allowed
Tool category 1/1E, 2, 3, and 4 materials	
Silicon Based Substrates and Films	
III/V compound Semiconductors	
Glass Substrates	
PECVD and ALD Films	
Cured organics and baked Photoresist	
CNF Class A, B, and Refractory metals	
Exposed Gold, Silver, Copper	
Alkali and Alkaline Compounds	
Organic/Biology Molecules prepared-w/salt buffers	
High Vapor Pressure Materials (Mg, Ca, Zn)*	* Some tool restrictions on high vapor pressure materials may apply
Soft organic materials	

High Vapor Pressure Metals and Compounds are materials that have a vapor pressure above 1e-6 Torr at 400 C.

Additional Material Restrictions and Exceptions

- Whole wafers or masks sized for available chucks only

Last Updated: 03/20/2025